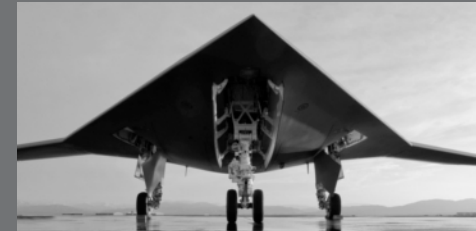




Ensuring Product Integrity with Truly Open Solutions

Steve Edwards and Ivan Straznicky



Ensuring Product Integrity with Truly Open Solutions

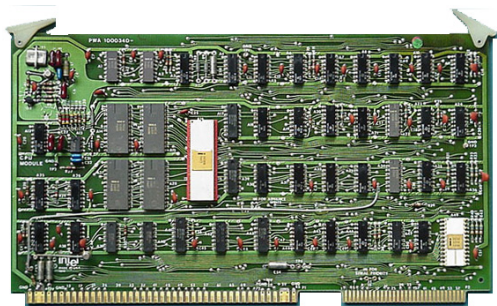
- **Steve Edwards will discuss:**
 - The challenges and solutions for ensuring product integrity for 10 Gbaud backplanes and beyond
 - The problem of processor “throttling”, which can detrimentally affect determinism in control systems.
- **Ivan Straznicky will discuss:**
 - Advanced cooling techniques to mitigate throttling that adhere to and extend VITA standards (vs. proprietary approaches) while also supporting RAND licensing models.



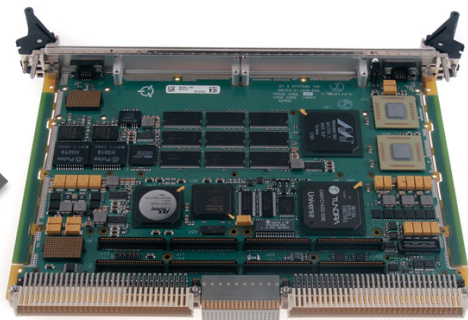
Ensuring product integrity for 10 Gbaud and beyond

Steve Edwards, Technical Fellow, Dir. Product Management – ISR Solutions

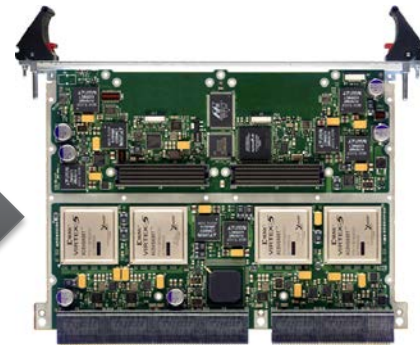
Ensuring product integrity for 10 Gbaud backplanes and beyond



MULTIBUS

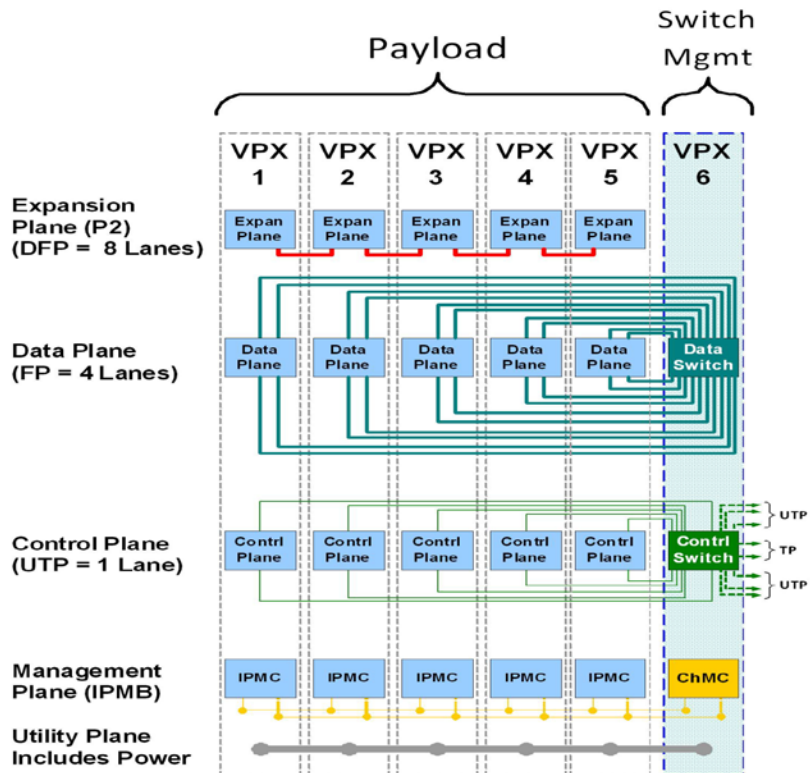


VME64



VPX

Ensuring product integrity for 10 Gbaud backplanes and beyond

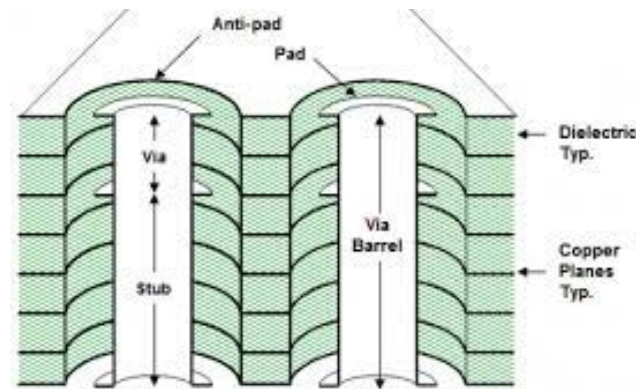
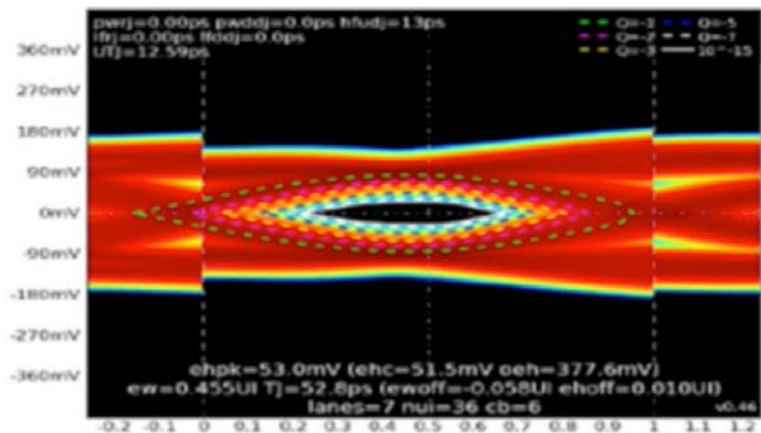


10.3 Gbaud 6-slot Central Switch Backplane

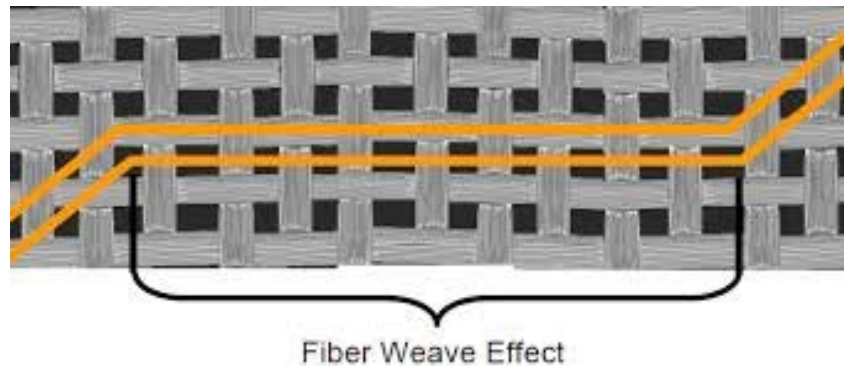
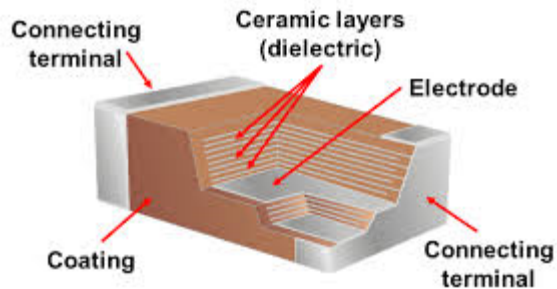


Rated at 6.25 GBaud

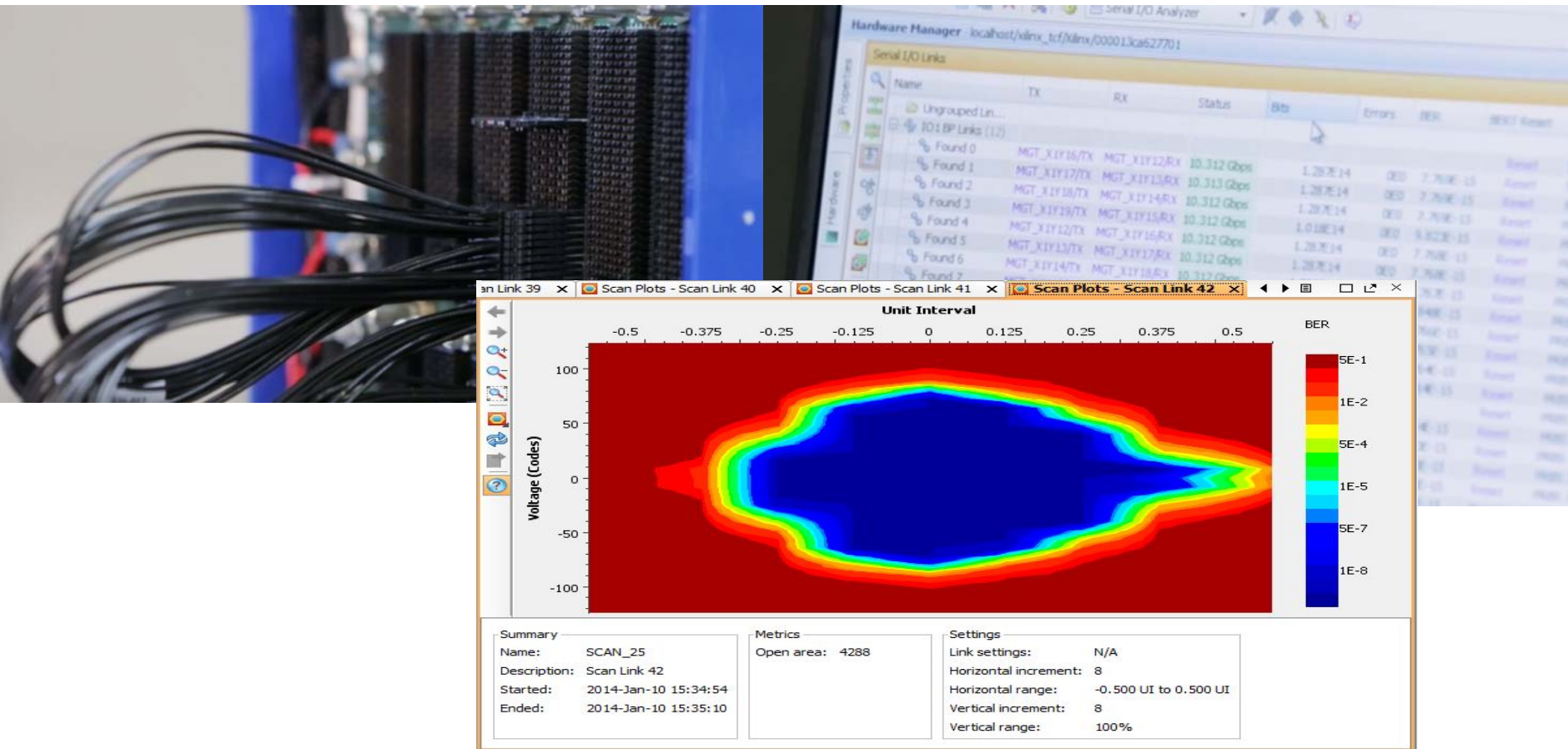
Ensuring product integrity for 10 Gbaud backplanes and beyond



Almost closed eye @ 10.3Gbaud



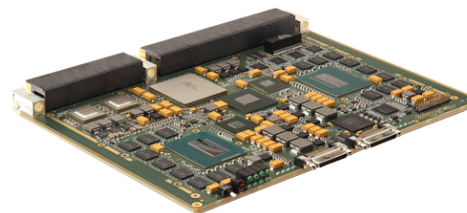
Ensuring product integrity for 10 Gbaud backplanes and beyond



Ensuring product integrity for 10 Gbaud backplanes and beyond

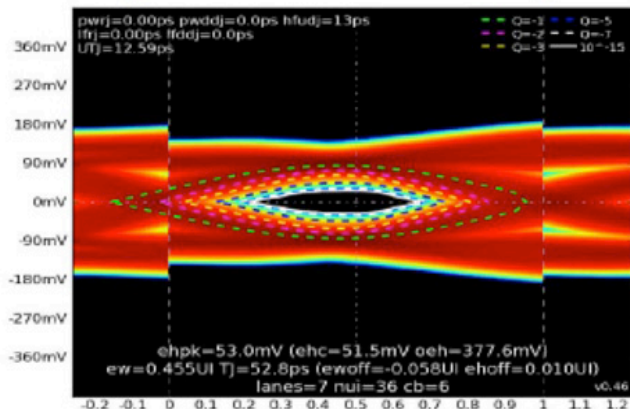
| Profile name | Data Plane 4 FP | | | | Expansion Plane | Control Plane 2 UTPs | | Control Plane 2 TPs | |
|-----------------------------|-------------------------|------|------|------|-----------------|----------------------|---------|---------------------|--------|
| | DP01 | DP02 | DP03 | DP04 | | CPUTp01 | CPUTp02 | CPTp01 | CPTp02 |
| MOD6-PAY-4F1Q2U2T-12.2.1-1 | SRIO 1.3 at 3.125 Gbaud | | | | PCIe Gen 1 | 1000BASE-BX | | 1000Base-T | |
| MOD6-PAY-4F1Q2U2T-12.2.1-2 | SRIO 1.3 at 3.125 Gbaud | | | | PCIe Gen 2 | 1000BASE-BX | | 1000Base-T | |
| MOD6-PAY-4F1Q2U2T-12.2.1-3 | PCIe Gen 1 | | | | PCIe Gen 1 | 1000BASE-BX | | 1000Base-T | |
| MOD6-PAY-4F1Q2U2T-12.2.1-4 | PCIe Gen 2 | | | | PCIe Gen 2 | 1000BASE-BX | | 1000Base-T | |
| MOD6-PAY-4F1Q2U2T-12.2.1-5 | 10GBASE-BX4 | | | | PCIe Gen 1 | 1000BASE-BX | | 1000Base-T | |
| MOD6-PAY-4F1Q2U2T-12.2.1-6 | 10GBASE-BX4 | | | | PCIe Gen 2 | 1000BASE-BX | | 1000Base-T | |
| MOD6-PAY-4F1Q2U2T-12.2.1-7 | 10GBASE-KX4 | | | | PCIe Gen 1 | 1000BASE-BX | | 1000Base-T | |
| MOD6-PAY-4F1Q2U2T-12.2.1-8 | 10GBASE-KX4 | | | | PCIe Gen 2 | 1000BASE-BX | | 1000Base-T | |
| MOD6-PAY-4F1Q2U2T-12.2.1-9 | SRIO 2.0 at 5.0 Gbaud | | | | PCIe Gen 2 | 1000BASE-BX | | 1000Base-T | |
| MOD6-PAY-4F1Q2U2T-12.2.1-10 | SRIO 2.0 at 6.25 Gbaud | | | | PCIe Gen 2 | 1000BASE-BX | | 1000Base-T | |
| MOD6-PAY-4F1Q2U2T-12.2.1-11 | SRIO 2.1 at 5.0 Gbaud | | | | PCIe Gen 2 | 1000BASE-BX | | 1000Base-T | |
| MOD6-PAY-4F1Q2U2T-12.2.1-12 | SRIO 2.1 at 6.25 Gbaud | | | | PCIe Gen 2 | 1000BASE-BX | | 1000Base-T | |
| MOD6-PAY-4F1Q2U2T-12.2.1-13 | InfiniBand DDR | | | | PCIe Gen 3 | 1000BASE-BX | | 1000Base-T | |
| MOD6-PAY-4F1Q2U2T-12.2.1-14 | 40GBase-KR4 | | | | PCIe Gen 2 | 1000BASE-BX | | 1000Base-T | |
| MOD6-PAY-4F1Q2U2T-12.2.1-15 | 40GBase-KR4 | | | | PCIe Gen 3 | 1000BASE-BX | | 1000Base-T | |
| MOD6-PAY-4F1Q2U2T-12.2.1-16 | InfiniBand QDR | | | | PCIe Gen 3 | 1000BASE-BX | | 1000Base-T | |
| MOD6-PAY-4F1Q2U2T-12.2.1-17 | InfiniBand FDR | | | | PCIe Gen 3 | 1000BASE-BX | | 1000Base-T | |

Proposed Gen 3 Data Rates

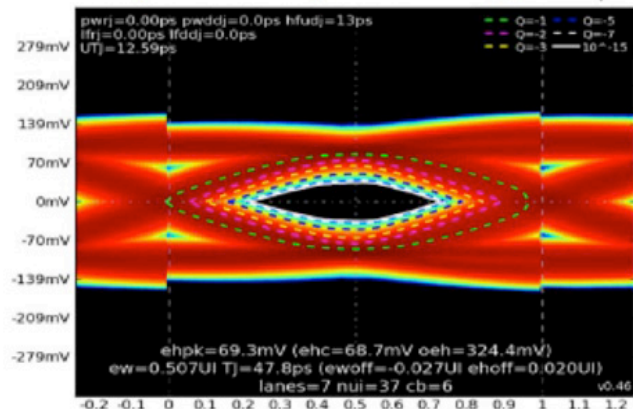



Ensuring product integrity for 10 Gbaud backplanes and beyond

Industry Design Rules
provide insufficient margin



Curtiss-Wright Design Rules
provide superior margin





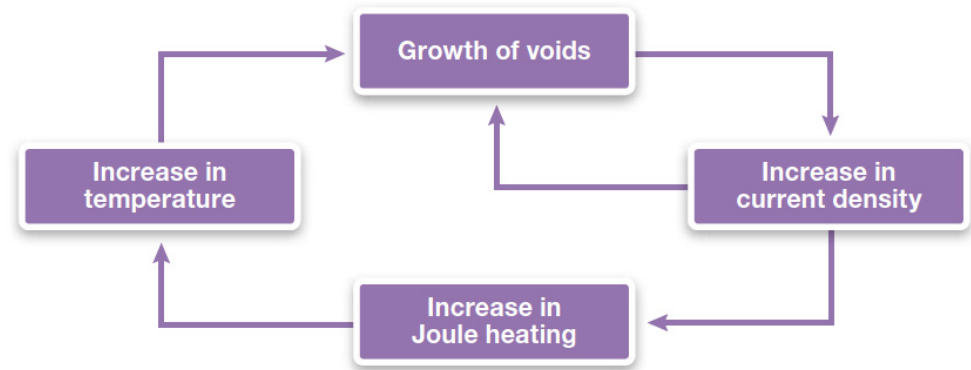
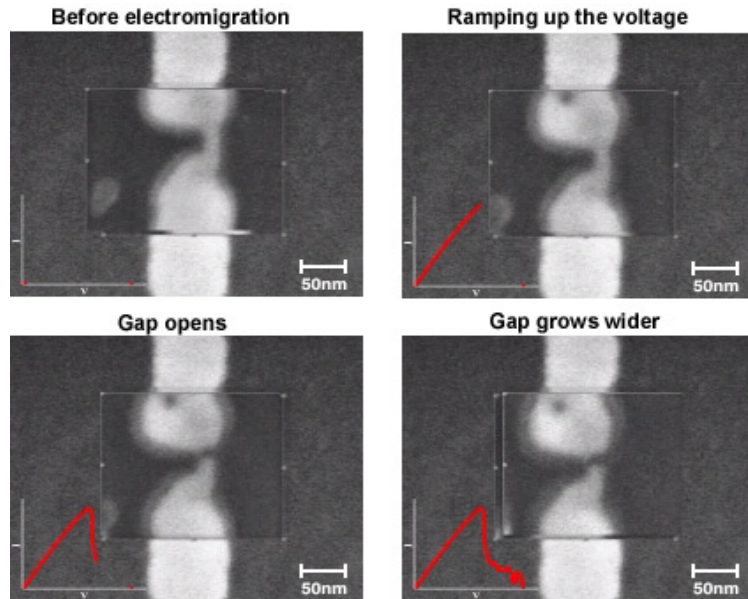
Advanced cooling techniques for High-Speed Systems

Ivan Straznicky, Technical Fellow, Curtiss-Wright Defense Solutions

HPC/HPEC

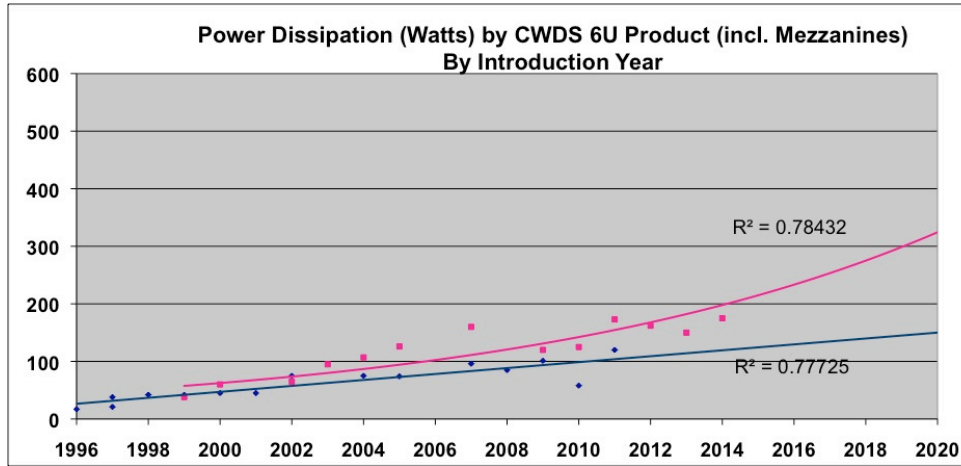


Electromigration



Thermal Management Overview

- Open standards based modules & chassis with innovative cooling



Liquid flow through module (US Patent #7,515,418)



Air flow through module

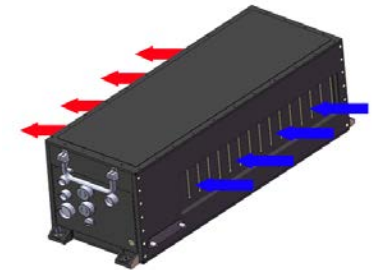
Rugged conduction module with embedded heat pipes (US Patent #6,839,235)



Rugged air cooled module

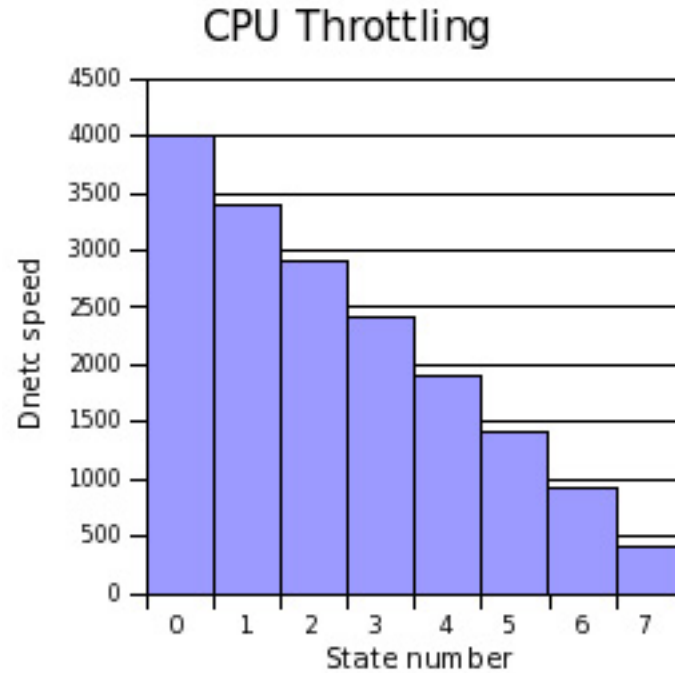
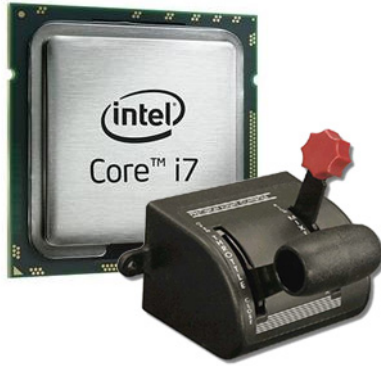


Liquid cooled sidewall chassis (>100W/slot) – Patent pending

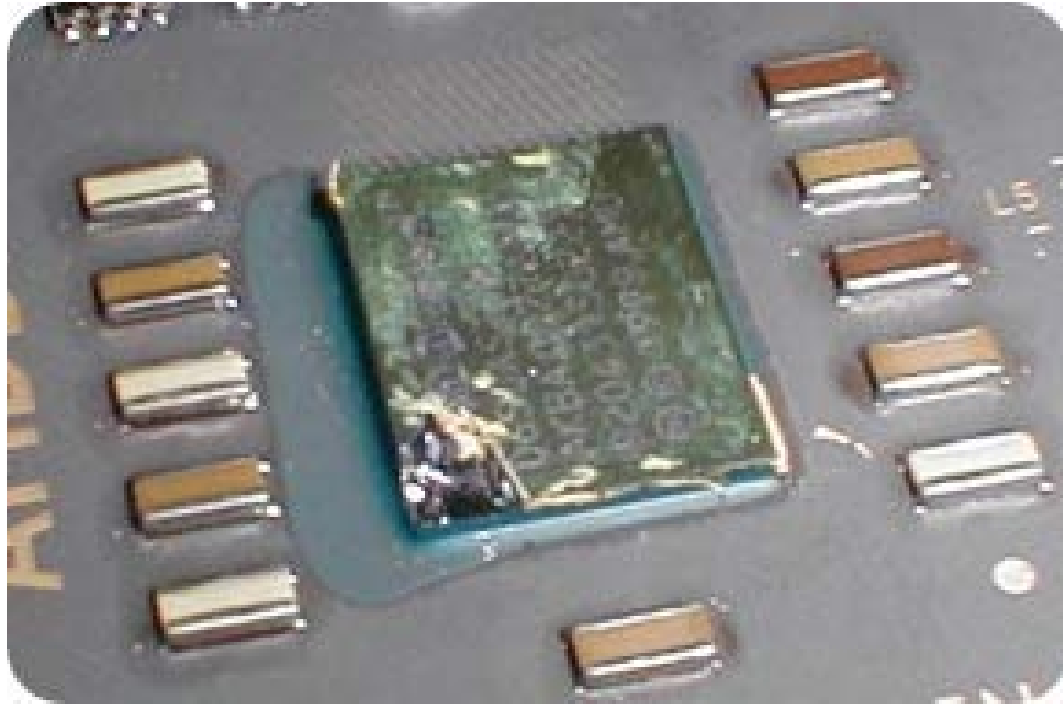


Air flow through chassis

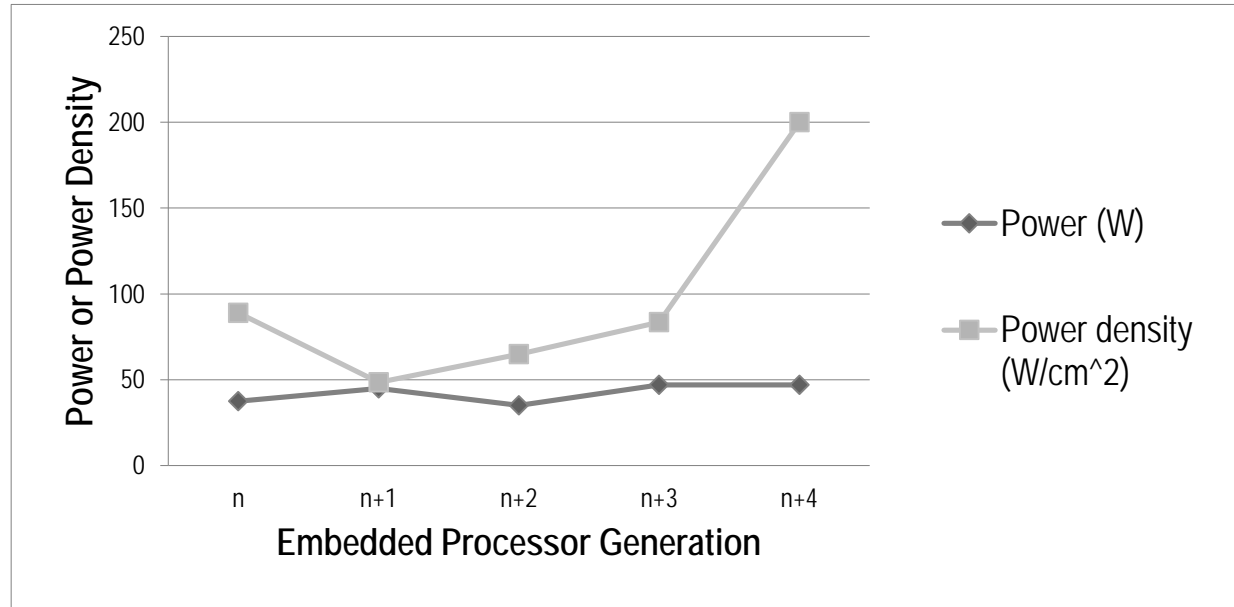
CPU Throttling



Thermal Runaway



Processor Power / Power Density



Air vs. Liquid



High Power Conduction (up to 470W)



The End

***CURTISS -
WRIGHT***

Q&A

www.cwcdefense.com